

Three Phase AC Controller Modules

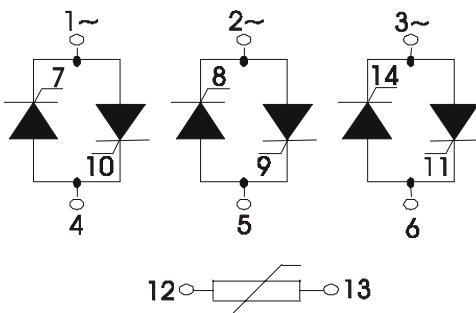
PSUT 115

I_{RMS}
V_{RRM}

= 3 x 115A
= 800-1600 V

Preliminary Data Sheet

V _{RSM} V _{DSM}	V _{RRM} V _{DRM}	Type
900	800	PSUT 115/08
1300	1200	PSUT 115/12
1500	1400	PSUT 115/14
1700	1600	PSUT 115/16



Symbol	Test Conditions		Maximum Ratings	
I _{RMS}	T _C = 85 °C		115	A
	T _C = 75 °C		141	A
I _{TAVM}	T _{VJ} = T _{VJM}		100	A
	T _{VSM}	T _{VJ} = 25°C	t = 10 ms (50 Hz), sine	1000 A
		t = 8.3 ms (60 Hz), sine	1100	A
$\int i^2 dt$	T _{VJ} = T _{VJM}	t = 10 ms (50 Hz), sine	870	A
		t = 8.3 ms (60 Hz), sine	950	A
(di/dt) _{cr}	T _{VJ} = T _{VJM}		120	A/μs
	f = 50Hz I _G = 0.6 A di _G /dt = 0.6 A/μs			
(dv/dt) _{cr}	T _{VJ} = T _{VJM}	V _{DR} = 0.67 V _{DRM}	1000	V/μs
	R _{GK} = ∞, method 1 (linear voltage rise)			
P _{GM}	T _{VJ} = T _{VJM}	t _P = 30μs	10	W
	I _T = I _{TAVM}	t _P = 300μs	5	W
P _{GAVM}			0.5	W
V _{RGM}			10	V
T _{VJ}			-40 ... + 125	°C
T _{VJM}			125	°C
T _{stg}			-40 ... + 130	°C
V _{ISOL}	50/60 HZ, RMS	t = 1 min	3000	V ~
	I _{ISOL} ≤ 1 mA	t = 1 s	3600	V ~
M _d	Mounting torque	M6	6	Nm
	Terminal connection torque	M6	6	Nm
Weight	typ.		290	g

Features

- Thyristor controller for AC (circuit W3C acc. to IEC) for mains frequency
- Isolation voltage 3000 V~
- Planar glasspassivated chips
- Package with metal base plate
- UL registered E 148688

Applications

- Switching and control of three phase AC circuits
- Light and temperature control
- Softstart AC motor controller
- Solid state switches

Advantages

- Easy to mount with two screws
- Space and weight savings
- Improved temperature and power cycling capability
- High power density

Symbol	Test Conditions		Characteristic Value		
I_D, I_R	$T_{VJ} = T_{VJM}$, $V_R = V_{RRM}$, $V_D = V_{DRM}$		\leq	10	mA
V_T	$I_T = 150A$, $T_{VJ} = T_{VJM}$		\leq	1.81	V
V_{TO}	For power-loss calculations only ($T_{VJ} = T_{VJM}$)			0.95	V
r_T				4.3	$m\Omega$
V_{GT}	$V_D = 6V$	$T_{VJ} = 25^\circ C$	\leq	2.5	V
I_{GT}	$V_D = 6V$	$T_{VJ} = 25^\circ C$	\leq	150	mA
V_{GD}	$T_{VJ} = T_{VJM}$	$V_D = 0.5 V_{DRM}$	\leq	0.2	V
I_{GD}	$T_{VJ} = T_{VJM}$	$V_D = 6 V$	\leq	5	mA
I_L	$T_{VJ} = 25^\circ C$, $t_P = 10\mu s$ $I_G = 0.6A$, $di_G/dt = 0.6A/\mu s$		\leq	600	mA
I_H	$T_{VJ} = 25^\circ C$, $V_D = 6V$, $R_A = 5\Omega$		\leq	200	mA
t_{gd}	$T_{VJ} = 25^\circ C$, $I_G = 0.6A$, $di_G/dt = 0.6A/\mu s$		\leq	1.2	μs
t_q	$T_{VJ} = T_{VJM}$, $I_T = 50A$, $t_P = 200\mu s$, $V_R = 100V$ $-di/dt = 10A/\mu s$, $dv/dt = 20V/\mu s$, $V_D = 2/3 V_{DRM}$			190	μs
R_{thJC}	per thyristor; sine 180° el			0.5	K/W
	per module; sine 180° el			0.083	K/W
R_{thJK}	per thyristor			0.7	K/W
	per module			0.12	K/W
d_s	Creeping distance on surface			12.5	mm
a	Max. allowable acceleration			50	m/s^2

Temperature sensor

R_{25}	Rated resistance, $T_c = 25^\circ C$	5	$k\Omega$
P_{25}	Power dissipation, $T_c = 25^\circ C$	max.	20 mW

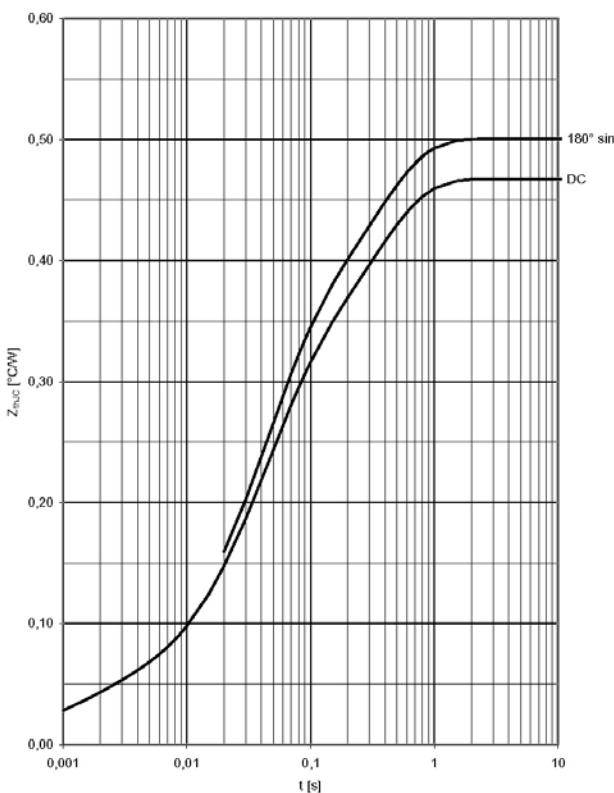


Fig. Transient thermal impedance per arm vs. time

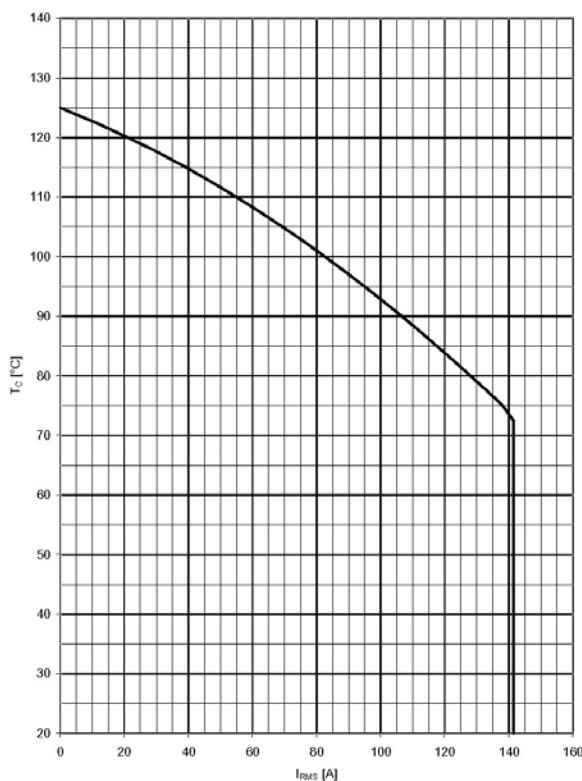


Fig. 2 Maximum allowable case temperature vs. RMS current

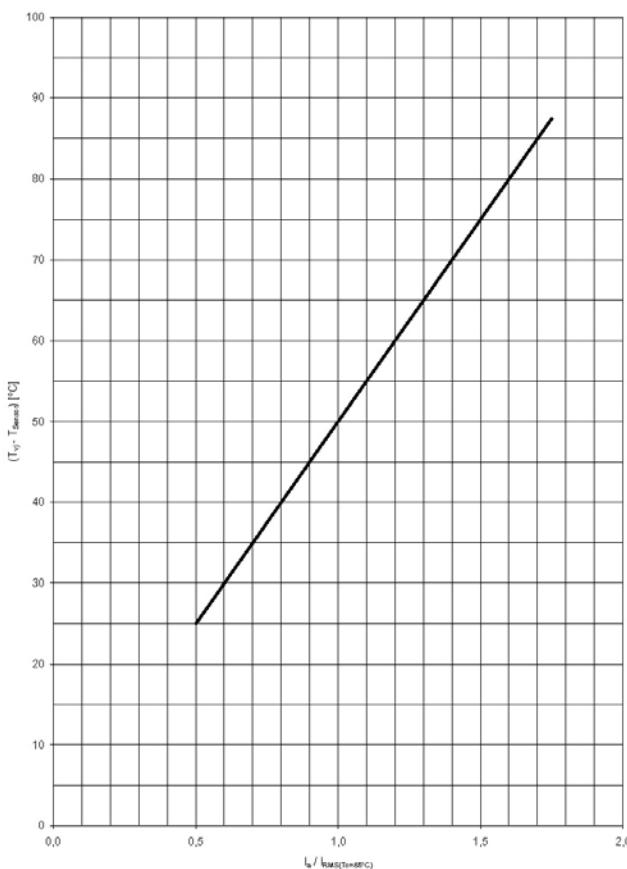


Fig. 3 Difference between the value of junction temperature and sensor temperature vs. starting current per RMS current

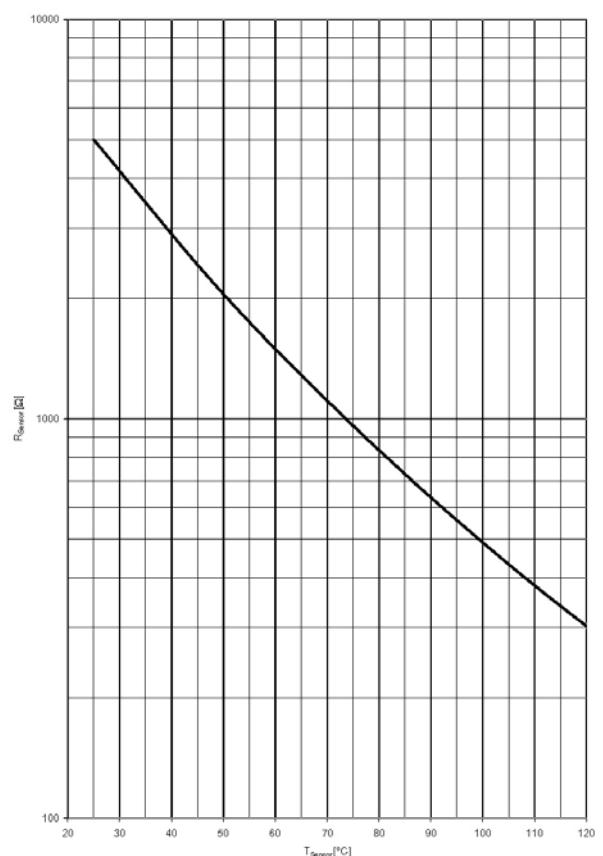


Fig. 4 Sensor resistance vs. sensor temperature

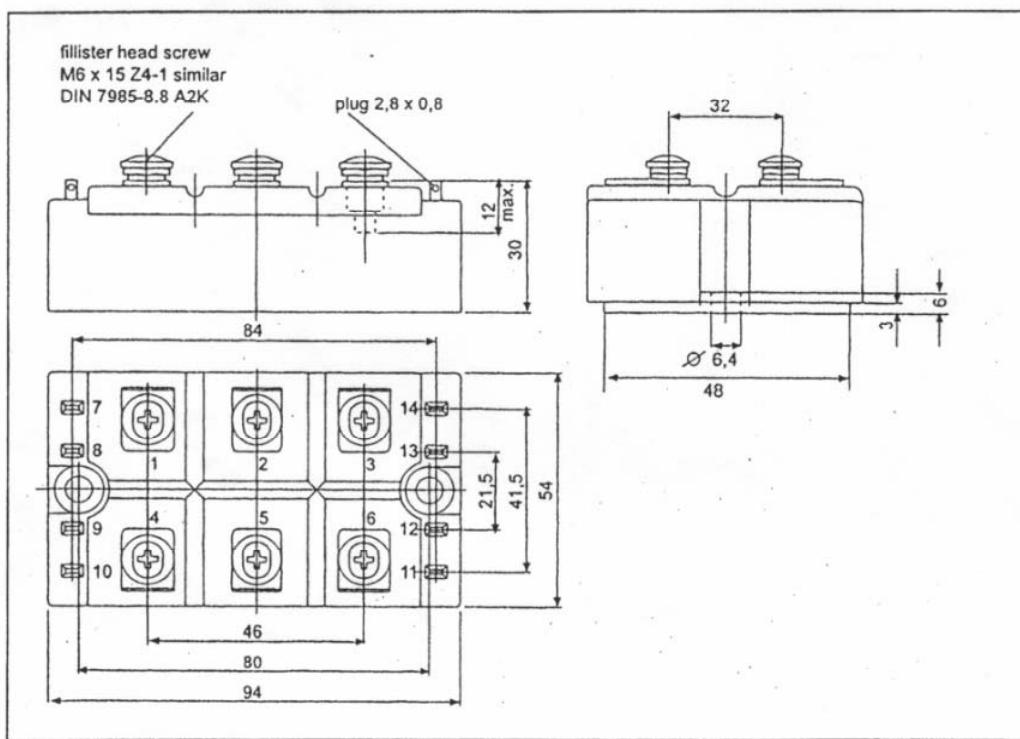


Fig. 5 Package style and outline